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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Not for submission under 37 CFR 1.99)

Application Number		10542040		
Filing Date		2006-02-06		
First Named Inventor	John I	Mize		
Art Unit		1795		
Examiner Name Jasor		Berman		
Attorney Docket Number		H0004870.70759 US -4015		

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Examiner Name	Jason Berman	
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